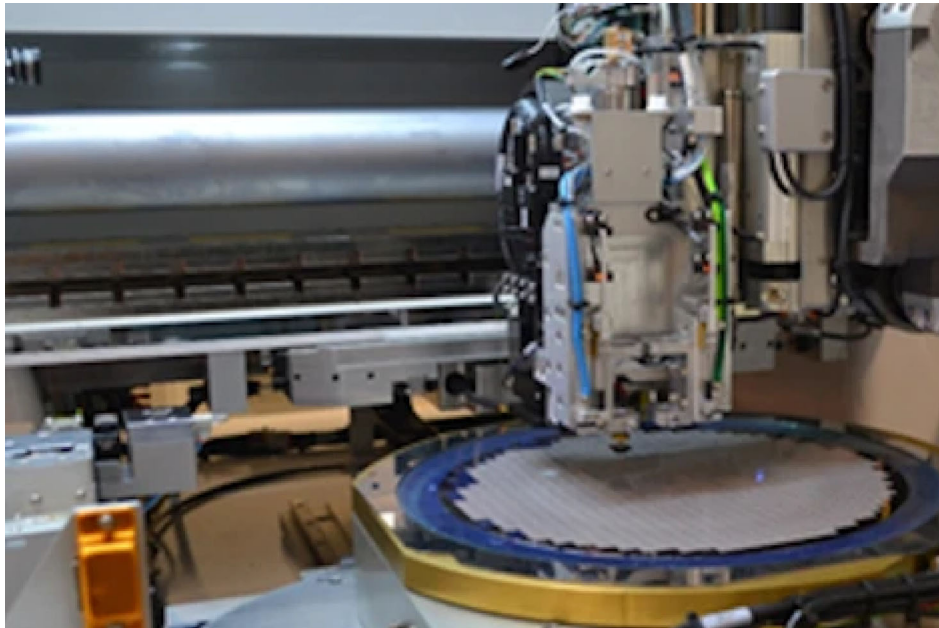




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MRSI values our customers, and our top priority is meeting our customers needs down to the finest detail. We are proud that all of our products are industry-leading, with superior flexibility, ultra-high-accuracy, and multiple process options. Our product's value is further illustrated by our 35+ years of experience in the industry in tandem with our 24/7 reliable field operations.



## **Die bonding - Ultra high precision Submicron-1 micron die bonders**

The MRSI-S-HVM submicron die bonder is designed for integrated photonics volume manufacturing applications, semiconductor wafer level packaging, multi-chips, and multi-process production in one machine. The MRSI-HVM1 and MRSI-H1 family provide proven superior flexibility for true multi-die, multi-process, and multi-product high volume high mix production, with < 1 micron accuracy.

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## **Die Bonding - High Speed 1.5 micron die bonders**

The MRSI-HVM and MRSI-H provide industry leading high-speed for high-volume manufacturing. These die bonding solutions are built with the same hardware and software platforms configured to minimize process deviations, reduce NPI cost, and increase ROI for customers with MRSI's long proven product reliability and global customer support.

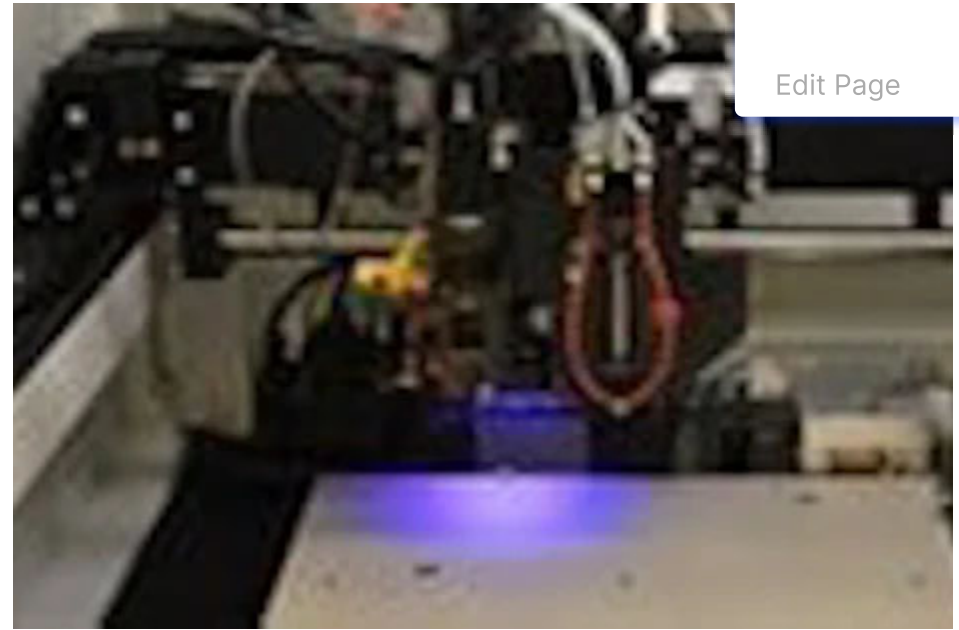
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### **Die Bonding Solutions delivering 3 and 5 micron accuracy MRSI-M3 and MRSI-705**

The ultra flexible MRSI-705 and MRSI-M3 can be used for research and development prototyping to low/medium volume. This medium-volume machine family includes all other machines' features with additions that facilitate a more precise experience. One featured highlight of the MRSI-M3 is that it uses an advanced cast composite base, enabling fast and accurate moves with no settling time. The large work envelope enables a wide range of configurations to meet customer requirements. While the MRSI-705 features a granite head that ensures the mechanism will not cantilever. Both machines demonstrate



### **High precision dispensing solutions MRSI-175Ag is a servo-controlled X, Y, and Z dispensing platform.**

The MRSI-175Ag Epoxy Dispenser handles the most demanding dispensing applications such as microwave modules, optical modules, hybrid circuits, multichip modules, and semiconductor packaging. With the ability to operate two heads in tandem, the MRSI-175Ag provides unparalleled process control and comprehensive dispensing capability. Die attach, underfill, encapsulation, and multi-pin stamping are all supported on this flexible dispensing platform.

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## Die bonding